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THERMALLY FUSIBLE HEAT-SENSITIVE TRANSFER SHEET

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Abstract:

PURPOSE: To lower a surface tension of ink, to suppress noise during transfer operation and to improve resolution of printing by providing a transfer layer wherein thermally fusible ink is applied onto one face of supporting material, and incorporating thermoplastic resin having a specific softening temperature and silicone surfactant which is in liquid state at a specific temperature in the thermally fusible ink.

CONSTITUTION: In a thermally fusible transfer sheet having supporting material and a transfer layer formed by applying thermally fusible ink onto one face of the supporting material, the ink contains viscous thermoplastic resin having softening temperature of 50W120°C and silicone surfactant which is in liquid state at the temperature of at least 15W50°C. Supporting material includes film or paper. Thermoplastic resin includes ethylcellulose, polyester resin, petroleum resin, ethylene-vinyl acetate copolymer, etc. having high compatibility with binder and coloring agent and proper viscosity. Non-ionic silicone surfactant having hydrophobic group composed of dimethyl silicone oil and hydrophilic group composed of polyether is employed.

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